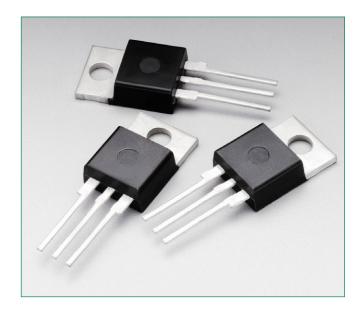


BTA25-600CW3G, BTA25-800CW3G





Description

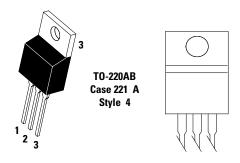
Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

Features

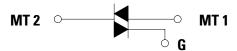
- Blocking Voltage to 800 V
- On-State Current Rating of 25 A RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/ dt – 500 V/µs minimum at 125°C
- Minimizes Snubber Networks for Protection

- Industry Standard TO-220AB Package
- High Commutating dl/ dt – 14 A/ms minimum at 125°C
- Internally Isolated (2500 V_{RMS})
- These are Pb-Free Devices and are RoHS Compliant

Pin Out



Functional Diagram



Additional Information







Resources



Samples

Maximum Ratings (T₁ = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) BTA25–600CW3G (Gate Open, Sine Wave 50 to 60 Hz, T_J = -40° to 125°C) BTA25–800CW3G	V _{DRM} , V _{RRM}	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T _c = 95°C)	I _{T (RMS)}	25	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_{\rm C}$ = 25°C)	I _{TSM}	250	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	260	A²sec
Non-Repetitive Surge Peak Off-State Voltage (T _J = 25°C, t = 8.3 ms)	V _{DSM} /V _{RSM}	V _{DSM} /V _{RSM} +100	V
Peak Gate Current (T _J = 110°C, t ≤ 20μs)	I _{GM}	4.0	W
Peak Gate Power (Pulse Width \leq 20 μ s, T_{c} = 80°C)	P _{G(AV)}	20	W
Average Gate Power (T _J = 110°C)	P _{G(AV)}	1.0	W
Operating Junction Temperature Range	T _J	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +125	°C
RMS Isolation Voltage (t = 300 ms, R.H. \leq 30%, T_A = 25°C)	V _{iso}	2500	V

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R _{ejc} R _{eja}	2.13 60	°C/W
Maximum Lead Temperature for Soldering Purpo 10 seconds	ses, 1/8" from case for	T_L	260	°C

Electrical Characteristics - OFF $(T_1 = 25^{\circ}\text{C unless otherwise noted}; \text{Electricals apply in both directions})$

Charac	teristic	Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T ₁ = 25°C	I _{DRM} ,	-	-	0.005	mΛ
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	$T_J^\circ = 110^\circ C$	I	-	-	2.0	mA

Electrical Characteristics - ON (T₁ = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Forward On-State Voltage (Note 2) ($I_{TM} = \pm 22.5 \text{ A Peak}$)		V _{TM}	-	-	1.55	V
	MT2(+), G(+)		2.0	_	35	
Gate Trigger Current (Continuous dc) ($V_D = 12 \text{ V}, R_L = 30 \Omega$)	MT2(+), G(-)	I _{GT}	2.0	_	35	mA
	MT2(-), G(-)		2.0	-	35	
Holding Current ($V_D = 12 \text{ V}$, Gate Open, Initiating Current = ±500 mA)		IH	-	_	50	mA
	MT2(+), G(+)		-	_	75	
Latching Current ($V_D = 12 \text{ V}, I_G = 12 \text{ mA}$)	MT2(+), G(-)	IL	-	_	75	mA
	MT2(-), G(-)		-	_	75	
	MT2(+), G(+)		0.5	-	1.3	
Gate Trigger Voltage ($V_D = 12 \text{ V}, R_L = 30 \Omega$)	MT2(+), G(-)	V _{GT}	0.5	-	1.3	V
	MT2(-), G(-)		0.5	-	1.3	
	MT2(+), G(+)		0.2	_	_	
Gate Non-Trigger Voltage ($T_J = 110$ °C)	MT2(+), G(-)	V _{GD}	0.2	-	-	V
-	MT2(-), G(-)		0.2	_	_	

^{2.} Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

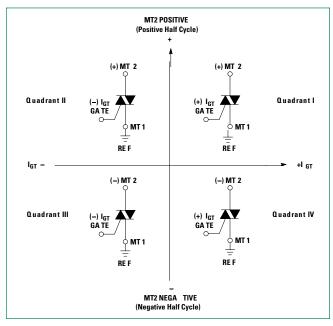
Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, $T_J = 110^{\circ}$ C, No Snubber)	(dl/dt)c	2.0	_	_	A/ms
Critical Rate of Rise of On–State Current ($T_J = 110^{\circ}\text{C}$, f = 120 Hz, $I_G = 20$ mA, tr ≤ 100 ns)	dl/dt	_	_	50	A/µs
Critical Rate of Rise of Off-State Voltage ($V_D = 0.66 \times V_{DRM}$, Exponential Waveform, Gate Open, $T_J = 110^{\circ}$ C)	dV/dt	250	_	_	V/µs

Voltage Current Characteristic of SCR

Symbol	Parameter		
V _{DRM}	Peak Repetitive Forward Off State Voltage		
I _{DRM}	Peak Forward Blocking Current		
V _{RRM}	Peak Repetitive Reverse Off State Voltage		
IRRM	Peak Reverse Blocking Current		
V_{TM}	Maximum On State Voltage		
I _H	Holding Current		

Quadrant Definitions for a Triac



All polarities are referenced to MT1 Witn in-phase signals (using standard AC lines) quadrants I and III are used.

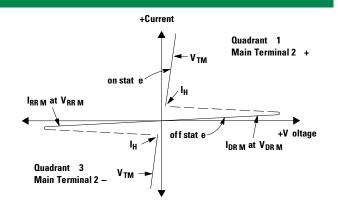




Figure 1. RMS Current Derating

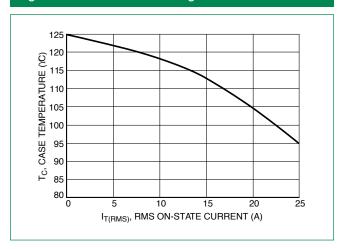


Figure 2. On-State Power Dissipation

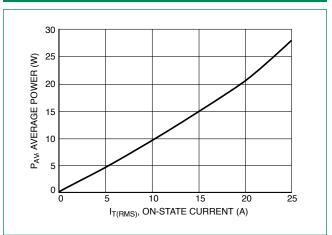


Figure 3. On-State Characteristics

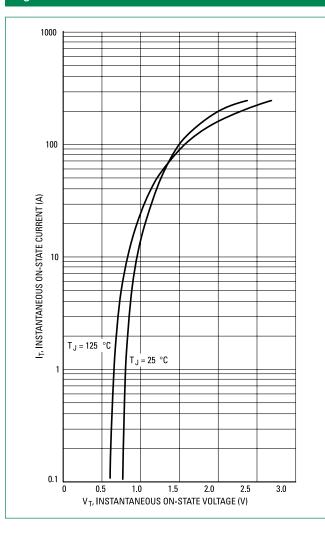


Figure 4. Thermal Response

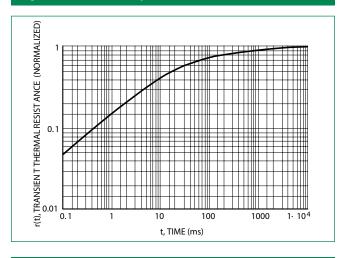


Figure 5. Hold Current Variation

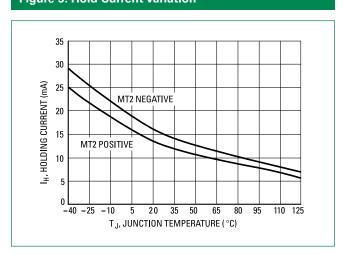




Figure 6. Gate Trigger Current Variation

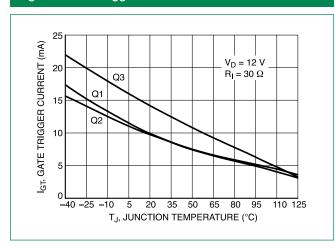


Figure 7. Gate Trigger Voltage Variation

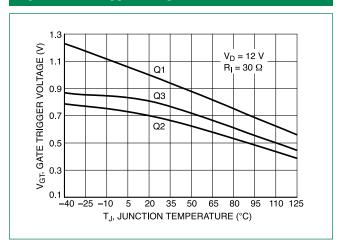


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential Waveform)

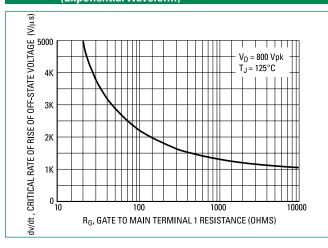


Figure 9. Latching Current Variation

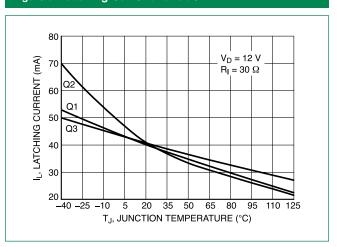
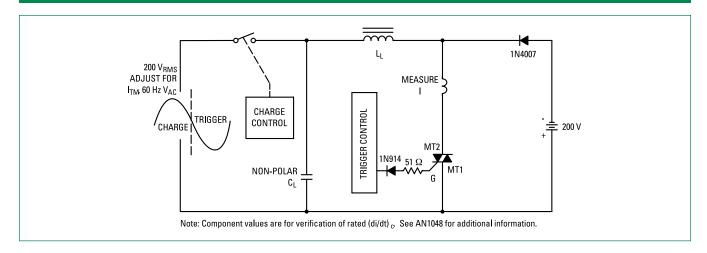
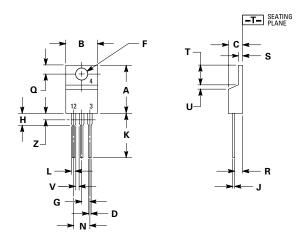


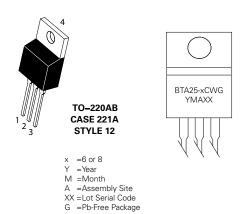
Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)



Dimensions



Part Marking System



Inches		Millin	neters	
Dim	Min	Max	Min	Max
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
Н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

Device		Package	Shippin
Ordering Informati	on		
4	No Connection		
3	Gate		
2	Main Terminal 2		

BTA25-800SW3G

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

Ordering Information		
Device	Package	Shipping
BTA25-600SW3G	TO-220AB	

TO-220AB

(Pb-Free)

500 Units / Rail

Pin Assignment

Main Terminal 1

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

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NTE5629 NTE5688 CTB08-400CW D31410 BTA425Z-800BTQ KS100N12 TOPT16-800C0,127 OT408,135 BT134-800E BT136D

BTB16Q-600BW Z0409MF BTA04-600B BTA06-600BRG BTA06-800BWRG BTA08-600BRG BTA08-800B BT136-600,127

MAC97A6,116 BT137-600E,127 BTB16-600CW3G BTB16-600CW3G Z0109MN,135 T825T-6I T1220T-6I NTE5638 ACST1235-8FP

BT136X-600E,127 MAC4DLM-1G BT134-600D,127 BTA08-600BW3G NTE56008 NTE56017 NTE56018 NTE56059 NTE5608

NTE5609 NTE5656 NTE56020 NTE56022